Qualcomm

RF360
Europe GmbH

Data sheet

SAW Rx filter
L Band

Series/type:	B8844
Ordering code:	B39152B8844P810
Date:	March 20, 2019
Version:	2.4

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1   Application

■ Low-loss Rx filter for L band
■ Usable pass band width 44MHz
■ Impedance at input and output 50Ω
■ Very low insertion attenuation
■ Unbalanced to unbalanced operation

2   Features

■ Package size 1.1$_{\pm0.1}$ mm × 0.9$_{\pm0.1}$ mm
■ Package height 0.45 mm (max.)
■ Approximate weight 1 mg
■ RoHS compatible
■ Package for Surface Mount Technology (SMT)
■ Ni/Au-plated terminals
■ Electrostatic Sensitive Device (ESD)
■ Moisture Sensitivity Level 3 (MSL3)
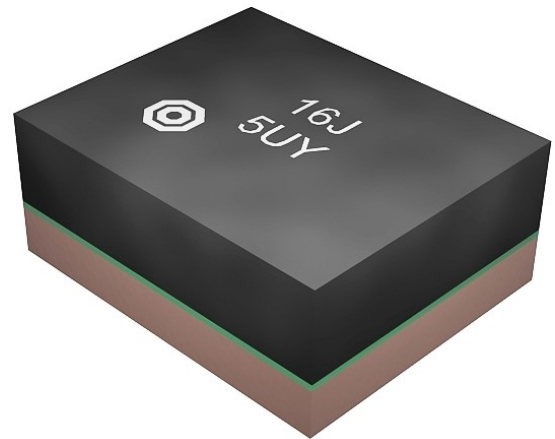
Figure 1: Picture of component with example of product marking.

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3 Package

BOTTOM VIEW
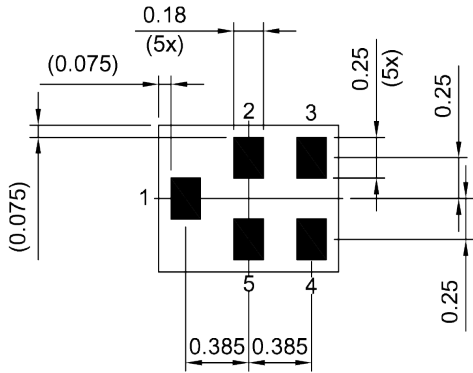
Pad and pitch tolerance ±0.05

4 Pin configuration

- ■ 1   Input
- ■ 4   Output
- ■ 2, 3, 5   Ground

SIDE VIEW
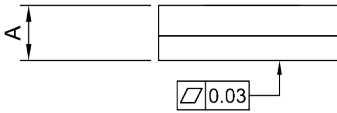
TOP VIEW
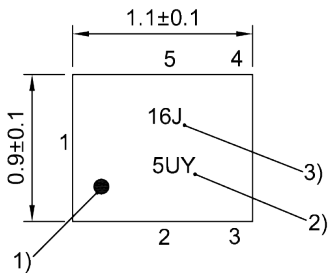
1) Marking for pad number 1

2) Example of encoded lot number

3) Example of encoded filter type number

Land pattern
THRU VIEW
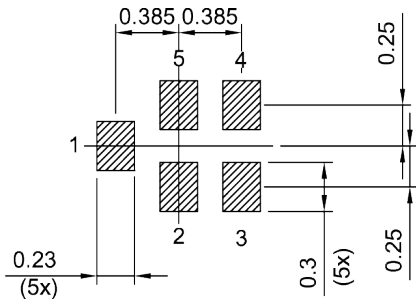
Landing pad tolerance -0.02

Figure 2: Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 19).

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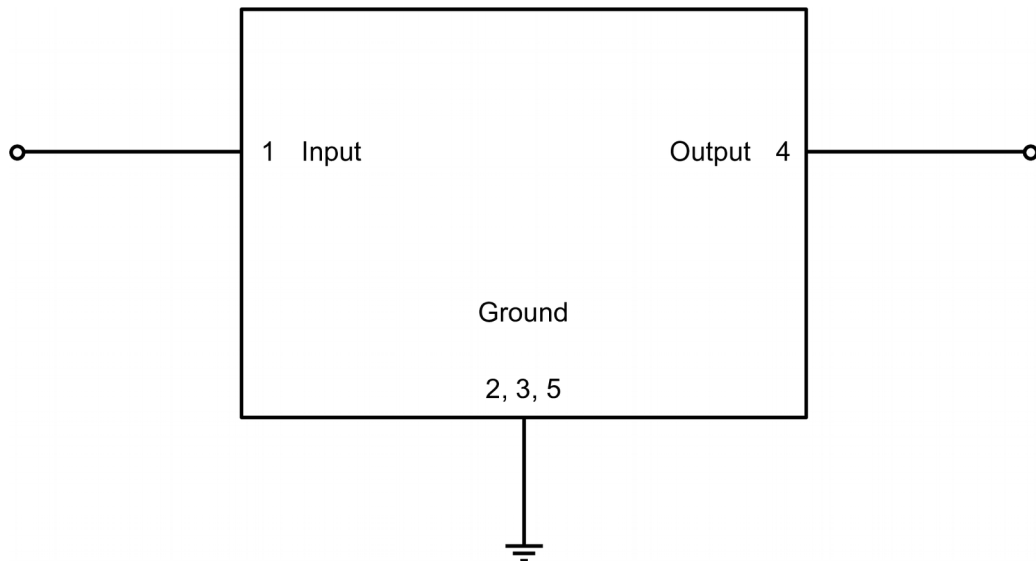
5   Matching circuit

Figure 3: Schematic of matching circuit. No external matching components required.

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6 Characteristics

Temperature range for specification T_{SPEC} = −30 °C ... +85 °C
Input terminating impedance Z_{IN} = 50 Ω
Output terminating impedance Z_{OUT} = 50 Ω

Characteristics				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency			f_C	—	1474	—	MHz
Maximum insertion attenuation			α_{max}				
	1452... 1496	MHz		—	1.7	2.3	dB
Amplitude ripple (p-p)			$\Delta\alpha$				
	1452... 1496	MHz		—	0.6	1.2	dB
Maximum VSWR			$VSWR_{max}$				
@ input port	1452... 1496	MHz		—	1.6	2.0	
@ output port	1452... 1496	MHz		—	1.6	2.0	
Maximum error vector magnitude			EVM_{max} [1]				
	1454.4... 1493.6	MHz		—	1.5	3.0	%
Minimum attenuation			α_{min}				
	800... 915	MHz		48	58	—	dB
	1530... 1570	MHz		20	32	—	dB
	1574... 1577	MHz		40	54	—	dB
	1710... 1785	MHz		46	54	—	dB
	1850... 1910	MHz		46	52	—	dB
	1920... 1980	MHz		46	52	—	dB
	2500... 2570	MHz		42	47	—	dB
	5000... 7000	MHz		30	37	—	dB

[1] Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

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7   Maximum ratings

Operable temperature	T_{OP}	= −40 °C ... +85 °C	
Storage temperature	T_{STG} [1]	= −40 °C ... +85 °C	
DC voltage	$|V_{DC}|$ [2]	= 0 V	
ESD voltage			
	V_{ESD} [3]	= 50 V	Machine model.
	V_{ESD} [4]	= 150 V	Human body model.
	V_{ESD} [5]	= 600 V	Charged device model.
Input power	P_{IN}		
@ input port: 832 ... 862 MHz		30 dBm[6]	Continuous wave for 10000 h @ 85 °C.
@ input port: 1452 ... 1496 MHz		16 dBm[6]	Continuous wave for 10000 h @ 85 °C.
@ input port: 1710 ... 1785 MHz		26 dBm[6]	Continuous wave for 10000 h @ 85 °C.
@ input port: 1920 ... 1980 MHz		30 dBm[6]	Continuous wave for 10000 h @ 85 °C.
@ input port: 2500 ... 2570 MHz		30 dBm[6]	Continuous wave for 10000 h @ 85 °C.

[1]   Not valid for packaging material. Storage temperature for packaging material is −25 °C to +40 °C.
[2]   In case of applied DC voltage blocking capacitors are mandatory.
[3]   According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.
[4]   According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.
[5]   According to JESD22-C101C (CDM – Field Induced Charged Device Model), 3 negative & 3 positive pulses.
[6]   Expected Life Time according to accelerated power durability simulation and wear out models.

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8   Transmission coefficient
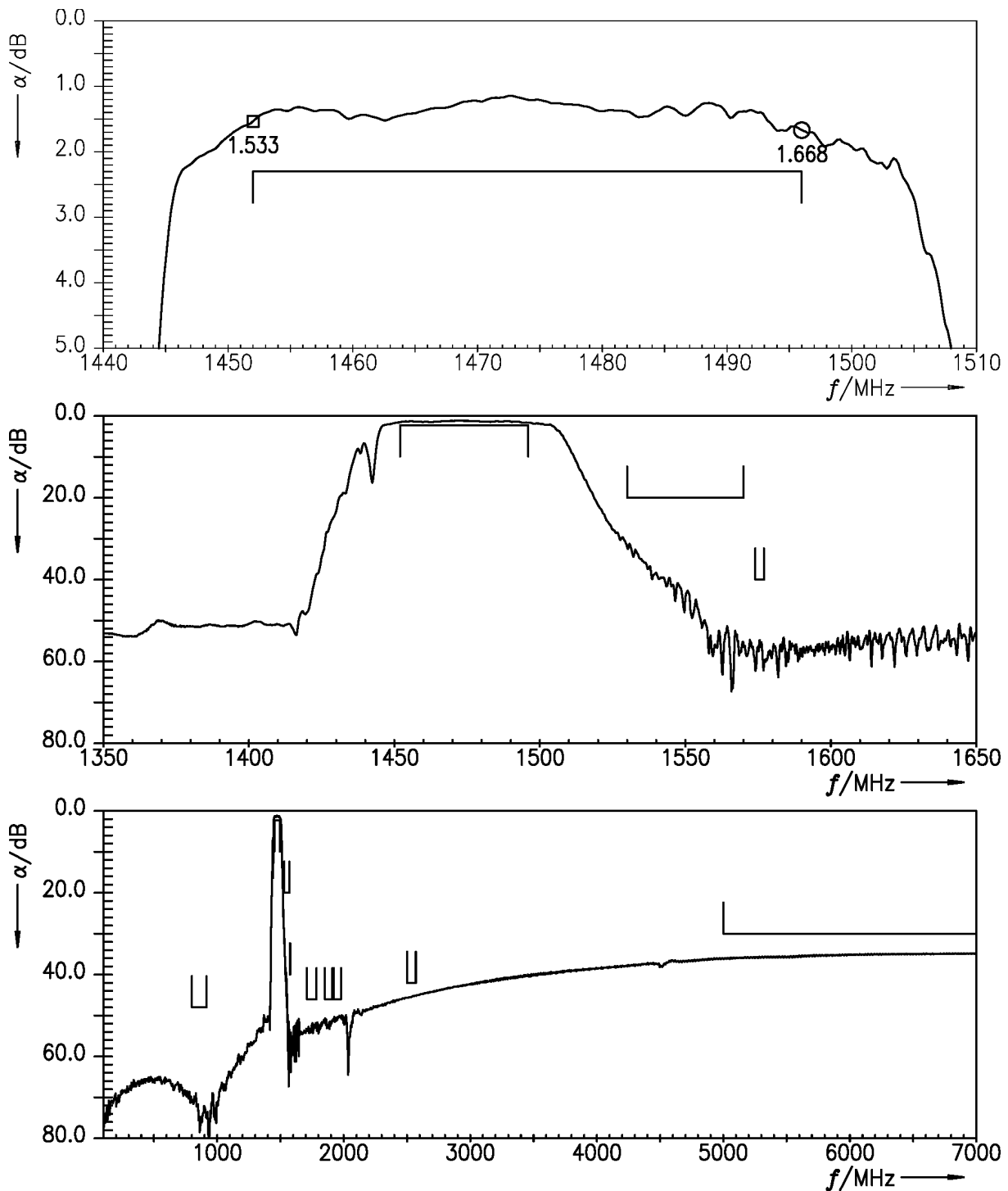
Figure 4: Attenuation .

9   Reflection coefficients
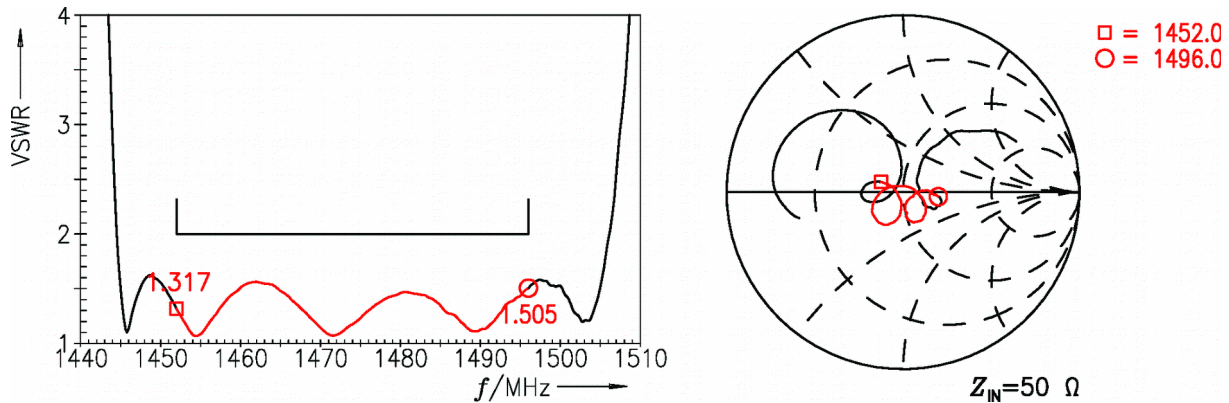
Figure 5: Reflection coefficient at input port.
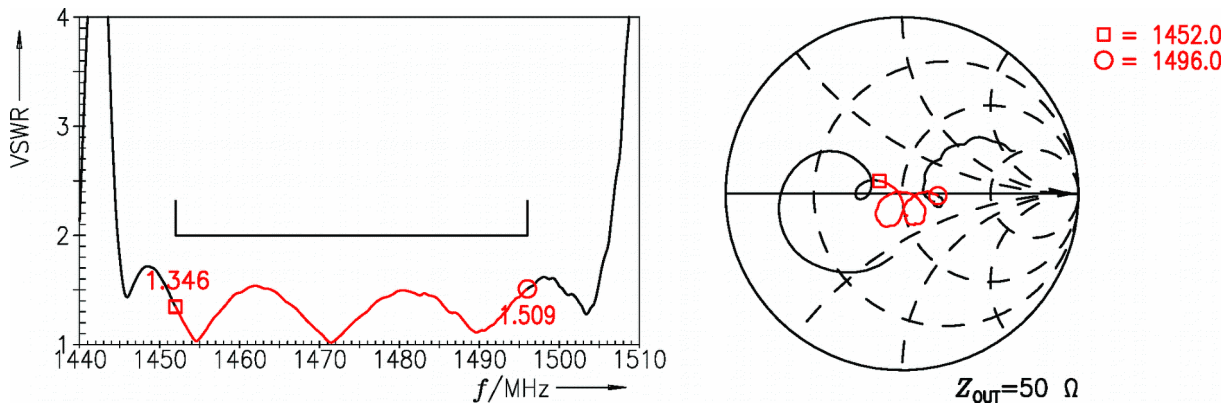
Figure 6: Reflection coefficient at output port.

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10   EVM
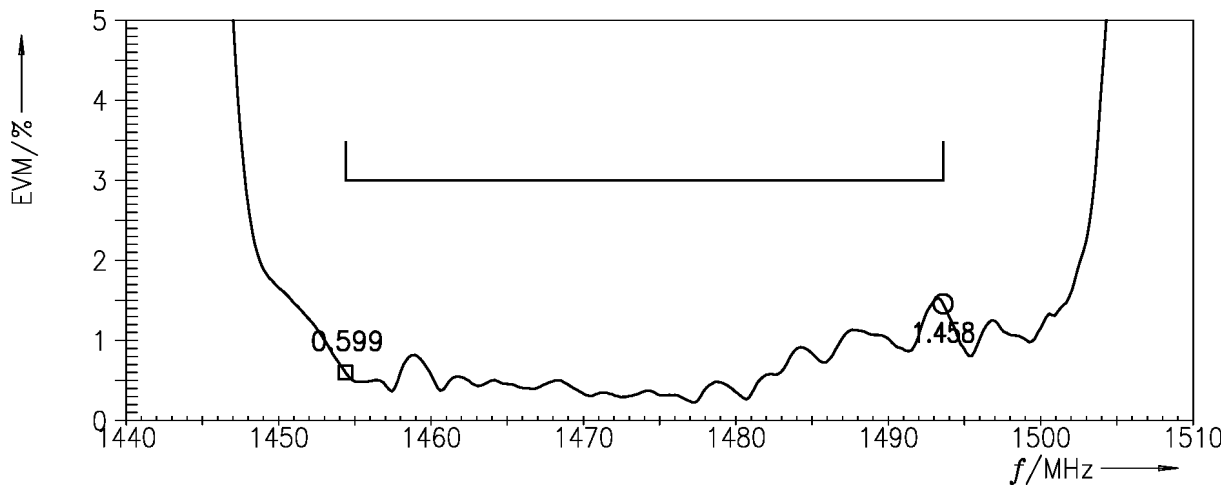
Figure 7: Error vector magnitude .

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11 Packing material

11.1 Tape
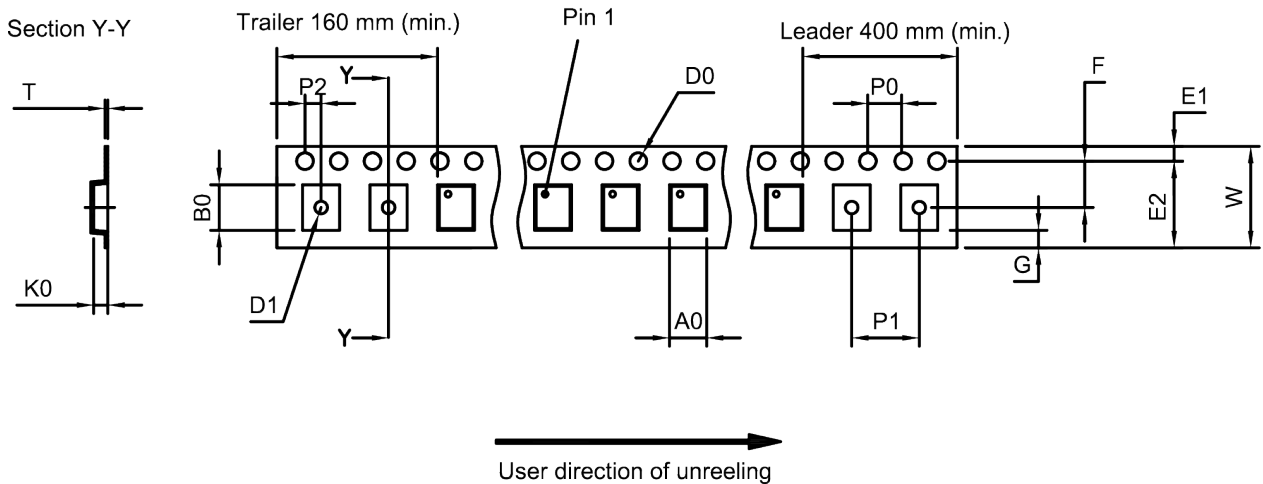
Figure 8: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A_0	1.02±0.05 mm	E_2	6.25 mm (min.)	P_1	2.0±0.1 mm
B_0	1.22±0.05 mm	F	3.5±0.05 mm	P_2	2.0±0.05 mm
D_0	1.55±0.05 mm	G	–	T	0.25±0.03 mm
D_1	0.55±0.1 mm	K_0	0.6±0.05 mm	W	8.0+0.3/−0.1 mm
E_1	1.75±0.1 mm	P_0	4.0±0.1 mm		

Table 1: Tape dimensions.

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11.2 Reel with diameter of 180 mm
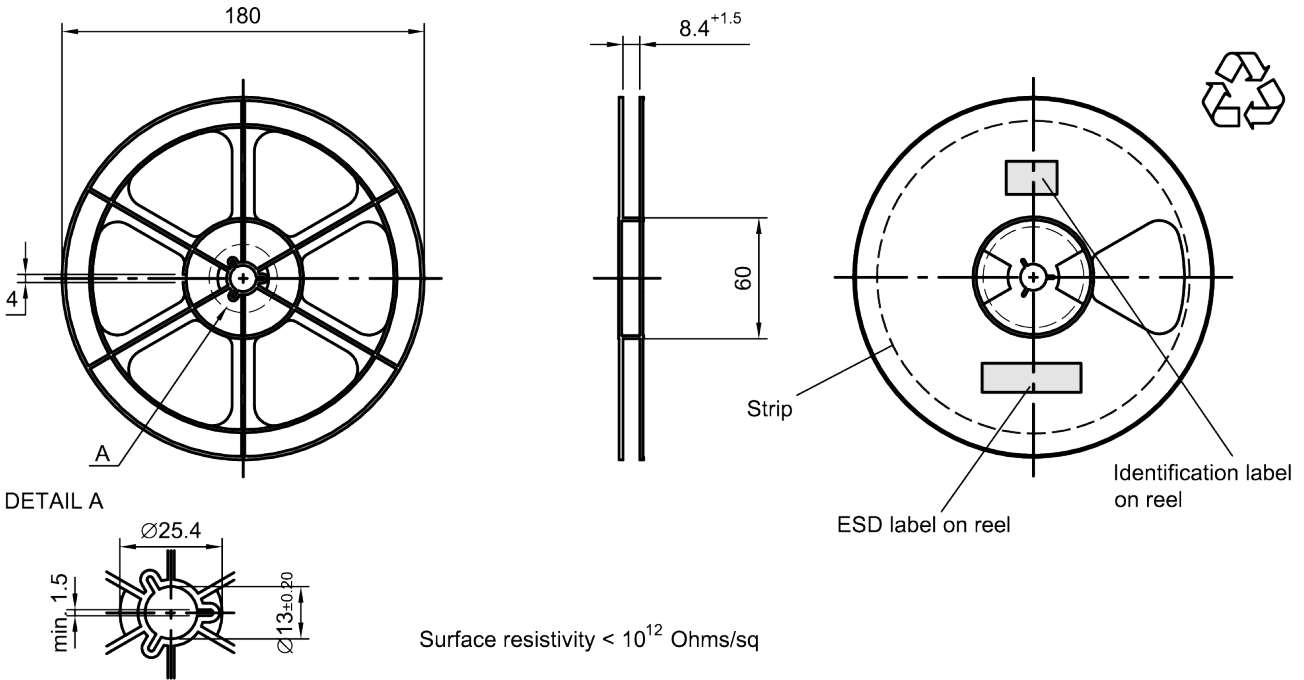
Figure 9: Drawing of reel (first-angle projection) with diameter of 180 mm.

Dimensions [mm]
X = 220+5
Y = 235+5
Sealing area 10±3

Figure 10: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

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Dimensions [mm]
L = 188
B = 188
H = 30
Tolerance ±5

2 pcs. ESD label
(around carton box)

Window for
customer label

Flat area of
moisture barrier bag
for customer label

Identification label
on carton box
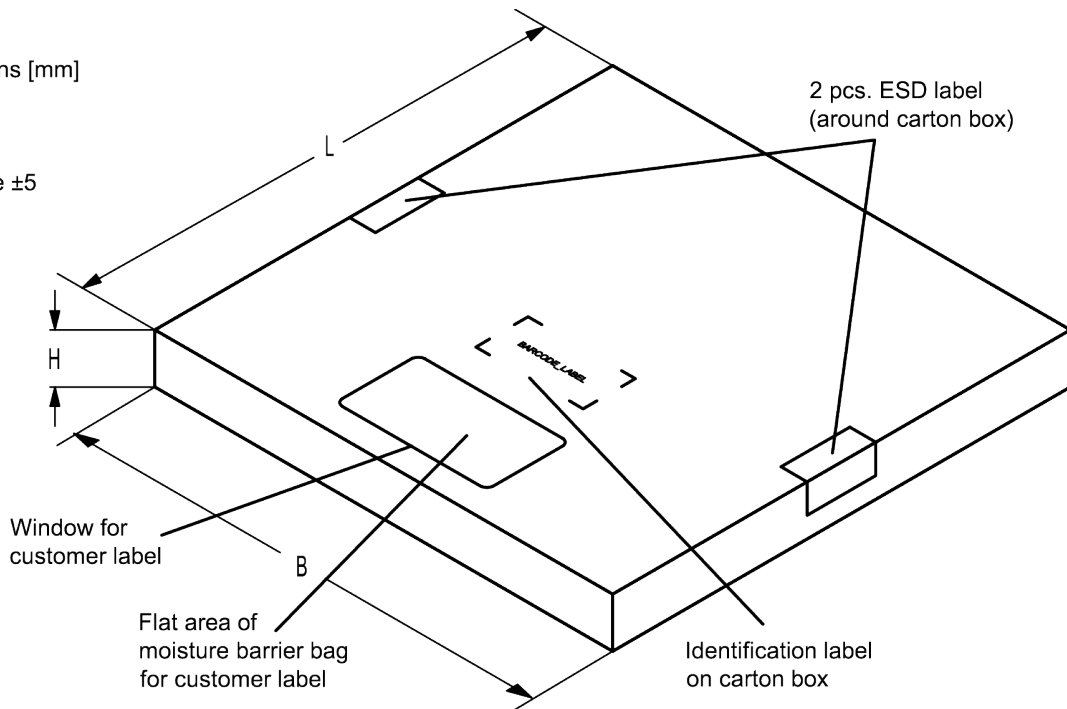
Figure 11: Drawing of folding box for reel with diameter of 180 mm.

11.3 Reel with diameter of 330 mm

330

$8.4 ^{+3}_{-0.5}$
(measure at
outer edge)

Supplier logo

100

A

14.4 max.
(measure at HUB)

Strip

$2 ^{+0.5}_{0}$

DETAIL A

$\varnothing 13 \pm 0.20$

21

4

ESD label on reel

Identification label
on reel

Surface resistivity < 10^{12} Ohms/sq
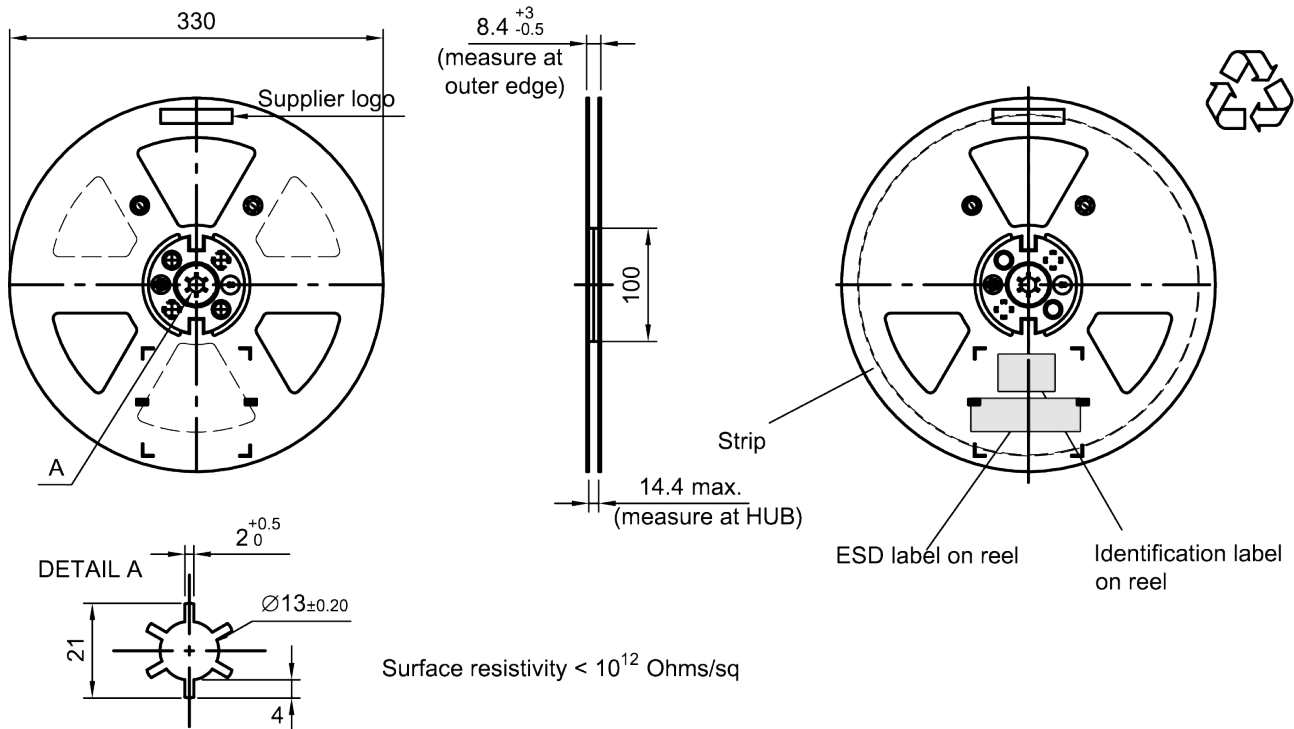
Figure 12: Drawing of reel (first-angle projection) with diameter of 330 mm.

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Dimensions [mm]
X = 400+5
Y = 418+5
Sealing area 10±3

Printing
on vacuumbag

Vacuumbag

Sealing area

Drypack
in vacuumbag

Identification label
on vacuumbag

Humidity indicator
in vaccumbag
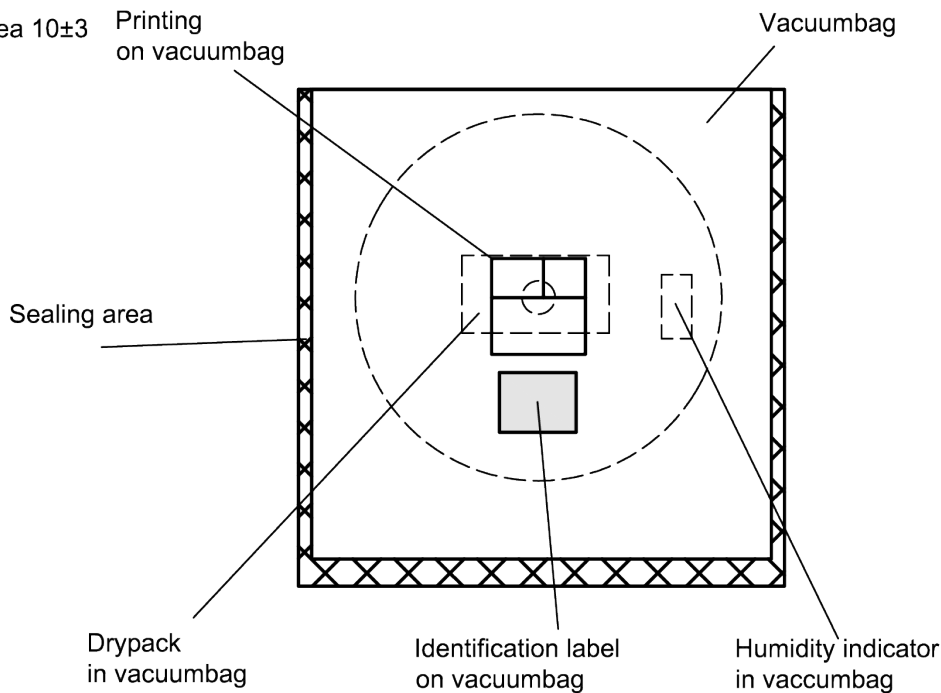
Figure 13: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

Dimensions [mm]
L = 335
B = 338
H = 36 (for 8 mm tape width)
    40 (for 12 mm tape width)
Tolerance ±5

2 pcs. ESD label
(around carton box)

Window for
customer label

Flat area of
moisture barrier bag
for customer label

Identification label
on carton box

In case of modules with
additional printing
for badge number
on the upper right side
on the top of the carton box.
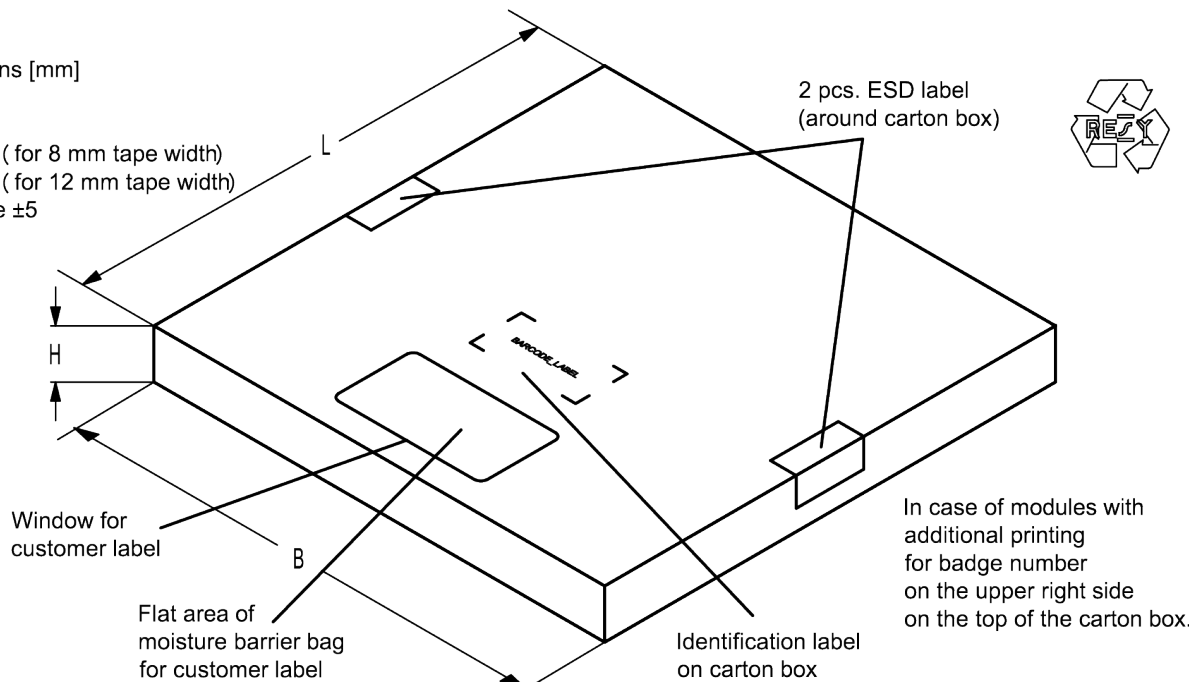
Figure 14: Drawing of folding box for reel with diameter of 330 mm.

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12 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code,   e.g., B3xxxxB**1234**xxxx,
is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding   type number marking on device   in decimal code.
         16J   **=>**   **1234**
         $\mathbf{1} \times 32^2 + \mathbf{6} \times 32^1 + \mathbf{18 (=J)} \times 32^0$ **=**   **1234**
The BASE32 code for product type B8844 is 8MC.

■ Lot number:

The last 5 digits of the lot number,   e.g.,   **12345**,
are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device   in decimal code.
         5UY   **=>**   **12345**
         $\mathbf{5} \times 47^2 + \mathbf{27 (=U)} \times 47^1 + \mathbf{31 (=Y)} \times 47^0$ **=**   **12345**

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

| Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

Table 2: Lists for encoding and decoding of marking.

13 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
$T > 220$ °C	30 s to 70 s
$T > 230$ °C	min. 10 s
$T > 245$ °C	max. 20 s
$T \geq 255$ °C	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).
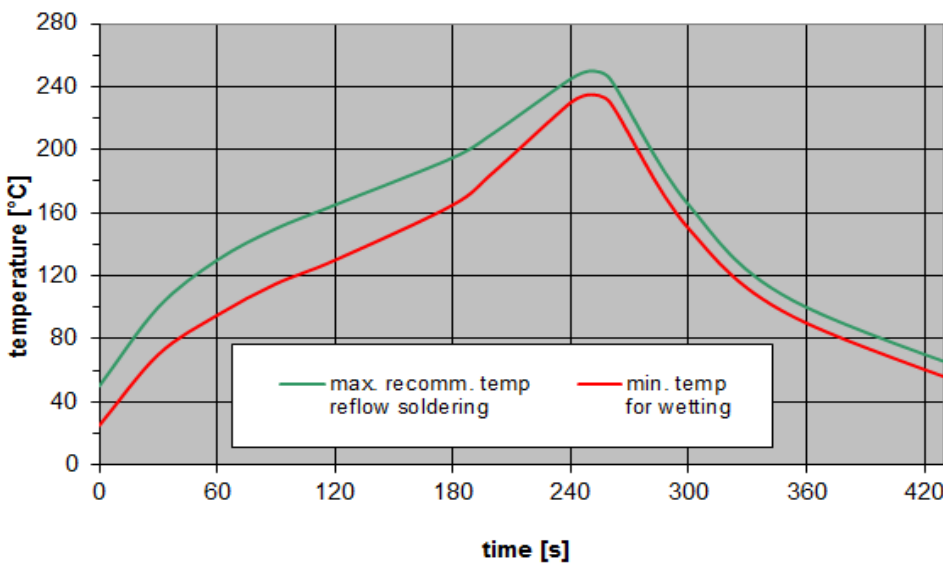
Figure 15: Recommended reflow profile for convection and infrared soldering – lead-free solder.

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14   Annotations

14.1   RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.2   Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

14.3   Ordering codes and packing units

Ordering code	Packing unit
B39152B8844P810	15000 pcs
B39152B8844P810 S 5	5000 pcs

Table 4: Ordering codes and packing units.

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15   Cautions and warnings

15.1   Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.rf360jv.com/orderingcodes.

15.2   Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

15.3   Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

15.4   Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.

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16   Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application.** As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.

2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified.** In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.

3. **The warnings, cautions and product-specific notes must be observed.**

4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet (www.rf360jv.com/material). Should you have any more detailed questions, please contact our sales offices.

5. We constantly strive to improve our products. Consequently, **the products described in this publication may change from time to time**. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order. We also **reserve the right to discontinue production and delivery of products**. Consequently, we cannot guarantee that all products named in this publication will always be available.
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